Product Change Notification / ASER-17HAXZ310

Date:

27-Aug-2021

Product Category:

Ethernet PHYs, Ethernet Switches, PCIe - Signal Integrity

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3740.004 Final Notice: Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages.

Affected CPNs:

ASER-17HAXZ310_Affected_CPN_08272021.pdf
ASER-17HAXZ310_Affected_CPN_08272021.csv

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages.

Pre and Post Change Summary:

	Pre Change	Post Change

Final Test Site	ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology Thailand (HQ) (MTAI)
Base Quantity Multiple (BQM)	No Changes. See Pre and Post Change Summary for comparison.		
Pin 1 Orientation	Chamfer Tray	Chamfer Tray	Chamfer Tray
Tray Stacking	5+1	5+1	5+1
Tray Dimension	No Changes. See Pre and Post Change Summary for comparison.		

Impacts to Data Sheet: None

Change Impact: None.

Reason for Change: To improve productivity by qualifying MTAI as an additional final test site
Change Implementation Status: In Progress

Estimated First Ship Date:
August 30, 2021 (date code: 2136)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2021				
Workweek	32	33	34	35	36
Qual Report Availability			X		
Final PCN Issue Date			X		
Estimated Implementation Date					X

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.
Revision History:
August 20, 2021: Issued final notification.
August 27, 2021: Reissued final notification. Updated estimated first ship date to August 30, 2021.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ASER-17HAXZ310_Pre and Post Change Summary.pdf
PCN_ASER-17HAXZ310_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

VSC8494YJE-12
VSC8494YJE-13
VSC8492YJD-13
VSC7227YKV
VSC7227YKV-01
VSC7511XMY
VSC7512XMY
VSC8489YJU
VSC8489YJU-10
VSC8489YJU-13
VSC8490YJU-10
VSC8490YJU-13
VSC8491YJU-13
VSC8489YJU-02
VSC8489YJU-16
VSC8489YJU-17
VSC8490YJU-17
VSC8491YJU-17
VSC8489YJU-01
VSC8489YJU-11
VSC8489YJU-14
VSC8489YJU-15
VSC8490YJU-11
VSC8490YJU-14
VSC8491YJU-11
VSC8491YJU-14
VSC3340XJJ-01
VSC3340XJJ-31
VSC8228XRC-01
VSC8484YJP
VSC8487YJU
VSC8487YJU-15
VSC8488YJU
VSC8488YJU-15
VSC8247YJB-01
VSC8247YJB-02
VSC8486YJB-11
VSC8658XHJ

CCB 3740.004
Pre and Post Change Summary
PCN #: ASER-17HAXZ310

A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages.

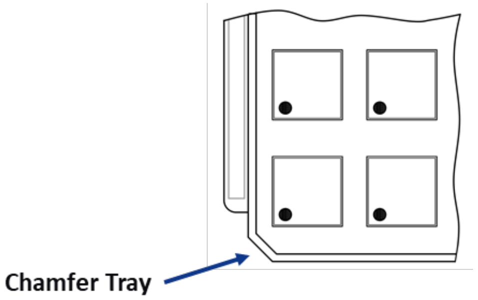
SMART | CONNECTED | SECURE

BQM per media

Item	Package Code	Package	Packing Media Type	ASE9	MTAI
1	4NC	HFCBGA 780 29x29mm	TRAY	36	36
2	3SC	HFCBGA 484 23x23mm	TRAY	60	60
3	2LC	FCCSP 144 13x13mm	TRAY	160	160
4	2MC	VQFN 172 13x13mm	TRAY	136	136
5	2TC	FCBGA 196 15x15mm	TRAY	126	126
6	3RC	HFCBGA 484 23x23mm	TRAY	60	60
7	3QC	TQFP 64 10x10	TRAY	160	160
8	3KC	HFCBGA 324 19x19mm	TRAY	84	84
9	2KC	FCCSP 144 13x13mm	TRAY	160	160
10	3PC	HSBGA 444 27x27mm	TRAY	40	40
11	3EC	PBGA 256 17x17mm	TRAY	90	90

Pin1 Orientation

Item	Package Code	Package	Packing Media Type	ASE9	MTAI
1	4NC	HFCBGA 780 29x29mm	TRAY	Chamfer Tray	Chamfer Tray
2	3SC	HFCBGA 484 23x23mm	TRAY	Chamfer Tray	Chamfer Tray
3	2LC	FCCSP 144 13x13mm	TRAY	Chamfer Tray	Chamfer Tray
4	2MC	VQFN 172 13x13mm	TRAY	Chamfer Tray	Chamfer Tray
5	2TC	FCBGA 196 15x15mm	TRAY	Chamfer Tray	Chamfer Tray
6	3RC	HFCBGA 484 23x23mm	TRAY	Chamfer Tray	Chamfer Tray
7	3QC	TQFP 64 10x10	TRAY	Chamfer Tray	Chamfer Tray
8	3KC	HFCBGA 324 19x19mm	TRAY	Chamfer Tray	Chamfer Tray
9	2KC	FCCSP 144 13x13mm	TRAY	Chamfer Tray	Chamfer Tray
10	3PC	HSBGA 444 27x27mm	TRAY	Chamfer Tray	Chamfer Tray
11	3EC	PBGA 256 17x17mm	TRAY	Chamfer Tray	Chamfer Tray

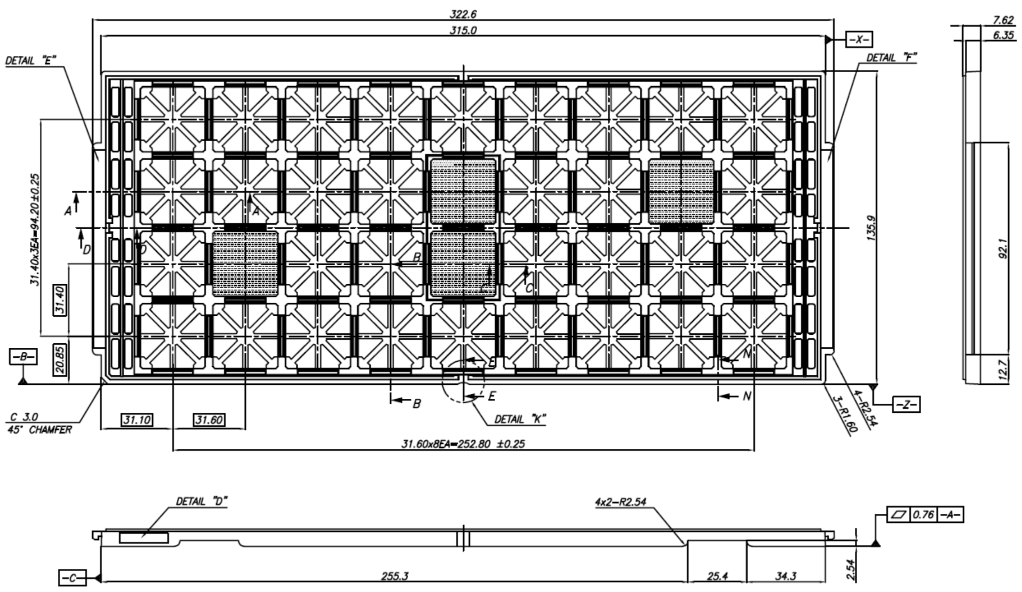


Tray Stacking

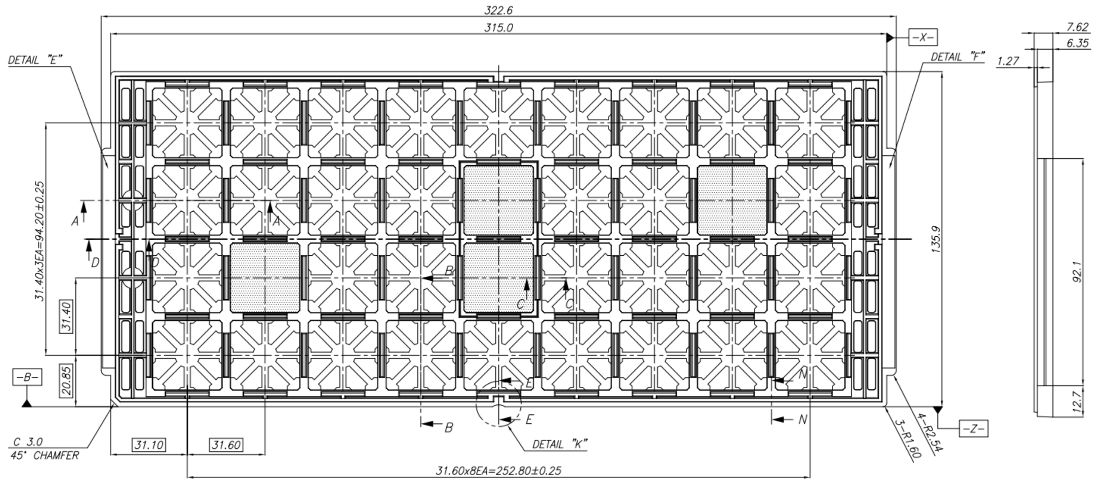
Item	Package Code	Package	Packing Media Type	ASE9	MTAI
1	4NC	HFCBGA 780 29x29mm	TRAY	5+1	5+1
2	3SC	HFCBGA 484 23x23mm	TRAY	5+1	5+1
3	2LC	FCCSP 144 13x13mm	TRAY	5+1	5+1
4	2MC	VQFN 172 13x13mm	TRAY	5+1	5+1
5	2TC	FCBGA 196 15x15mm	TRAY	5+1	5+1
6	3RC	HFCBGA 484 23x23mm	TRAY	5+1	5+1
7	3QC	TQFP 64 10x10	TRAY	5+1	5+1
8	3KC	HFCBGA 324 19x19mm	TRAY	5+1	5+1
9	2KC	FCCSP 144 13x13mm	TRAY	5+1	5+1
10	3PC	HSBGA 444 27x27mm	TRAY	5+1	5+1
11	3EC	PBGA 256 17x17mm	TRAY	5+1	5+1

4NC (HFCBGA 780L 29x29mm) Tray drawing

ASE9

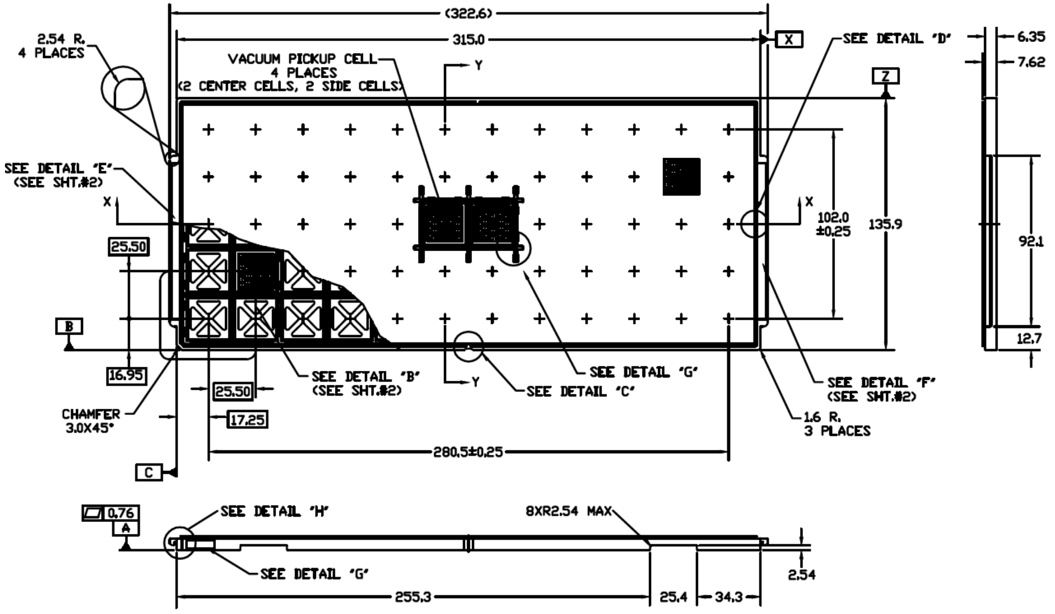
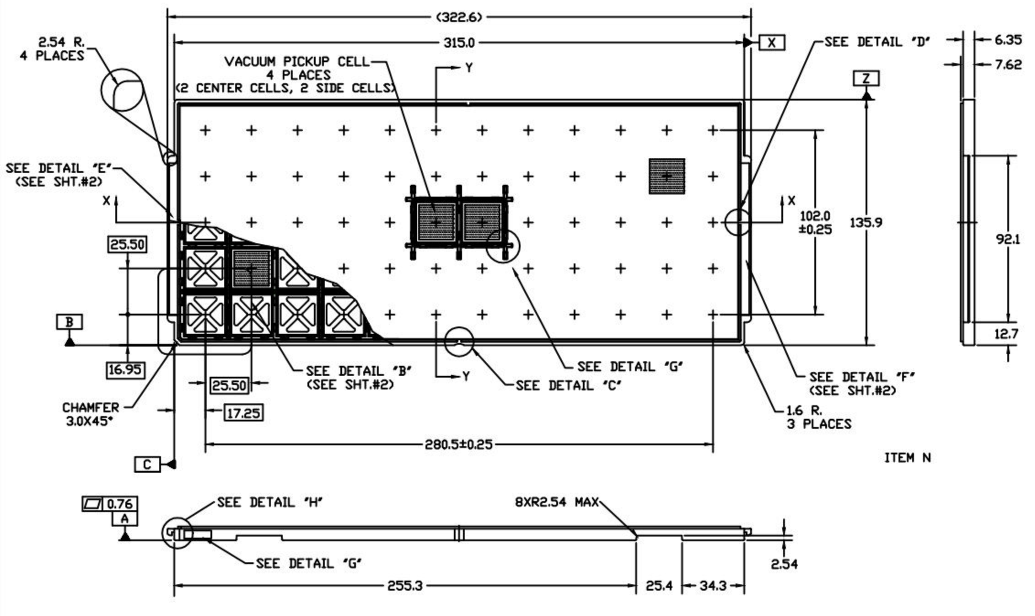


MTAI



Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	4	9	36	31.60	31.40	31.10	20.85	5+1
MTAI	150C	4	9	36	31.60	31.40	31.10	20.85	5+1

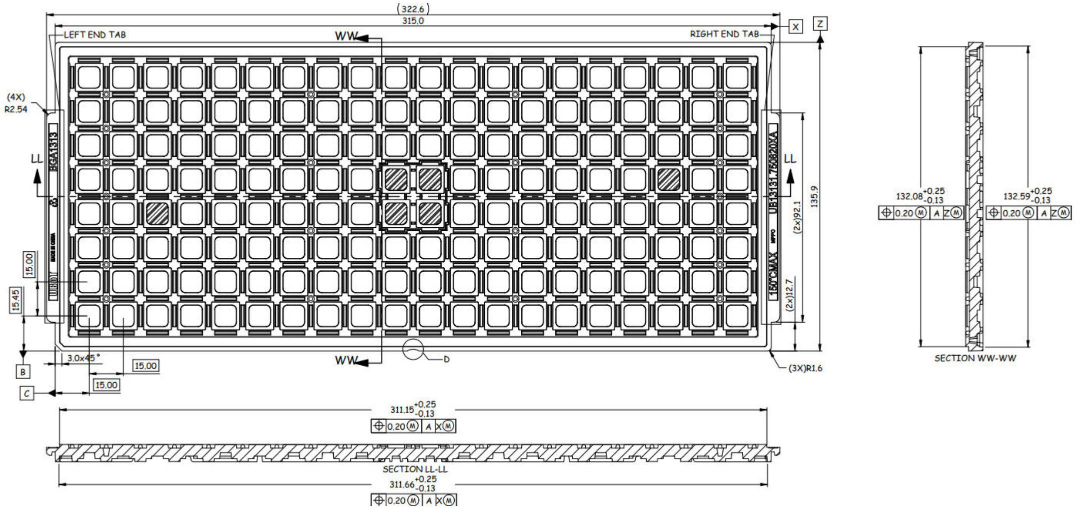
3RC and 3SC (HFCBGA 484L 23x23mm) Tray drawing

ASE9	MTAI
	

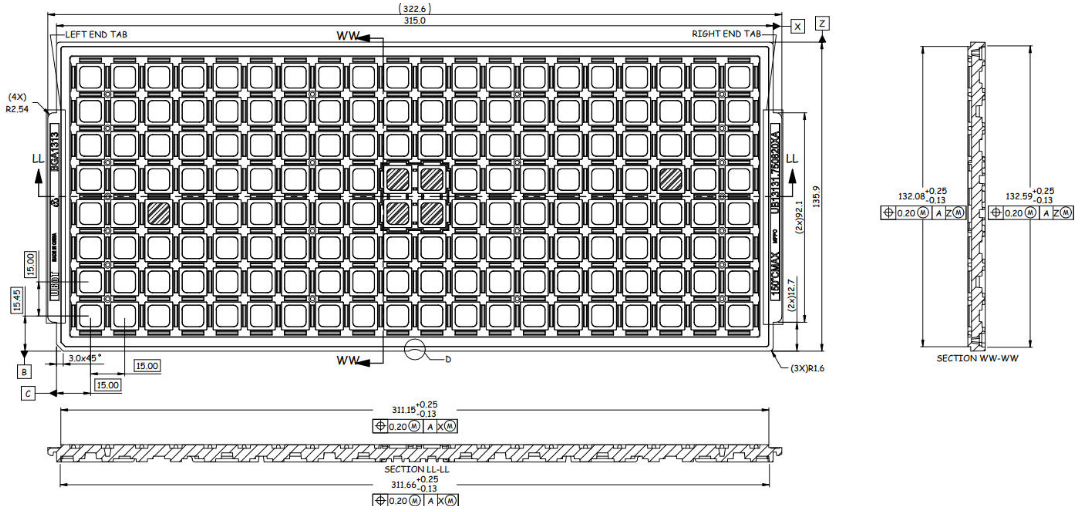
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	5	12	60	25.50	25.50	17.25	16.95	5+1
MTAI	150C	5	12	60	25.50	25.50	17.25	16.95	5+1

2KC and 2LC (FCCSP 144L 13x13mm) Tray drawing

ASE9



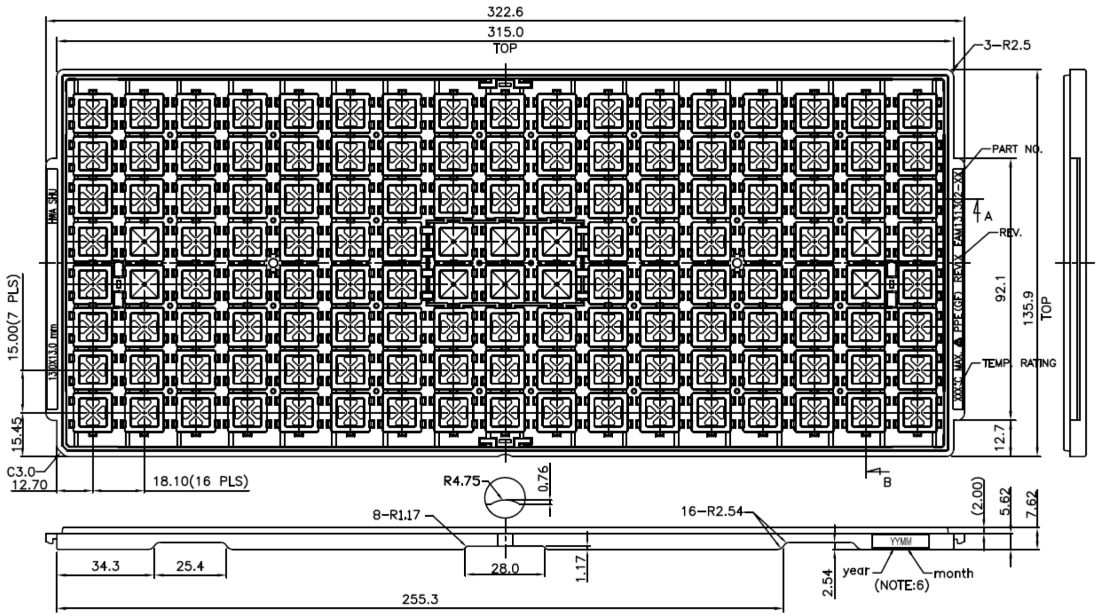
MTAI



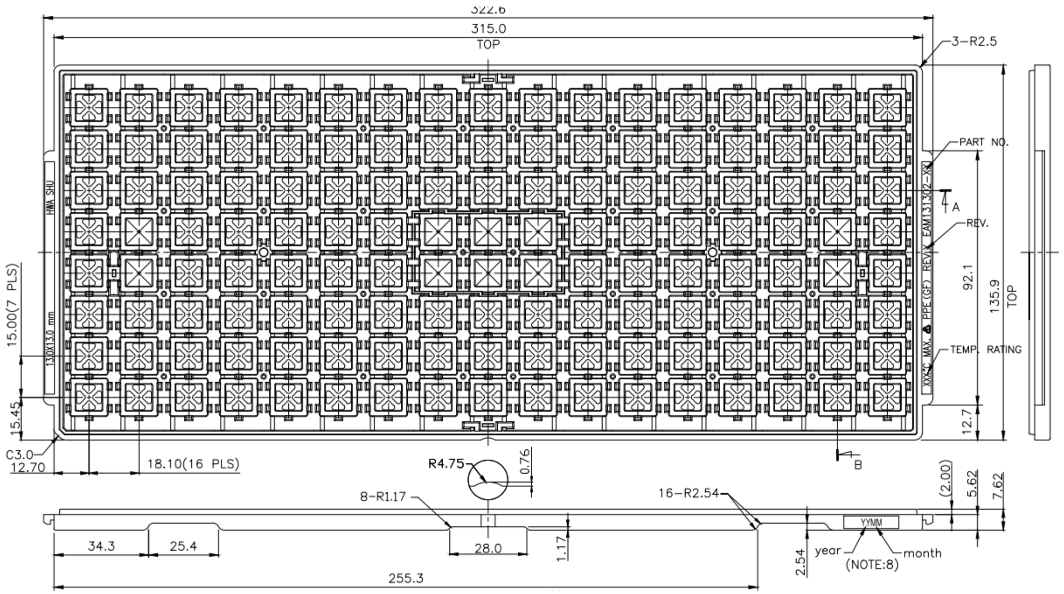
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	8	20	160	15.00	15.00	15.00	15.45	5+1
MTAI	150C	8	20	160	15.00	15.00	15.00	15.45	5+1

2MC (VQFN 172L 13x13x0.9mm) Tray drawing

ASE9



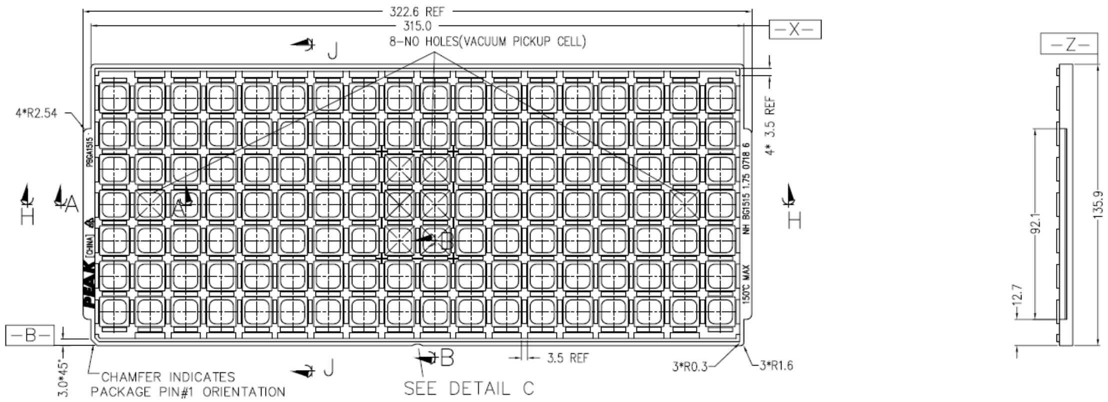
MTAI



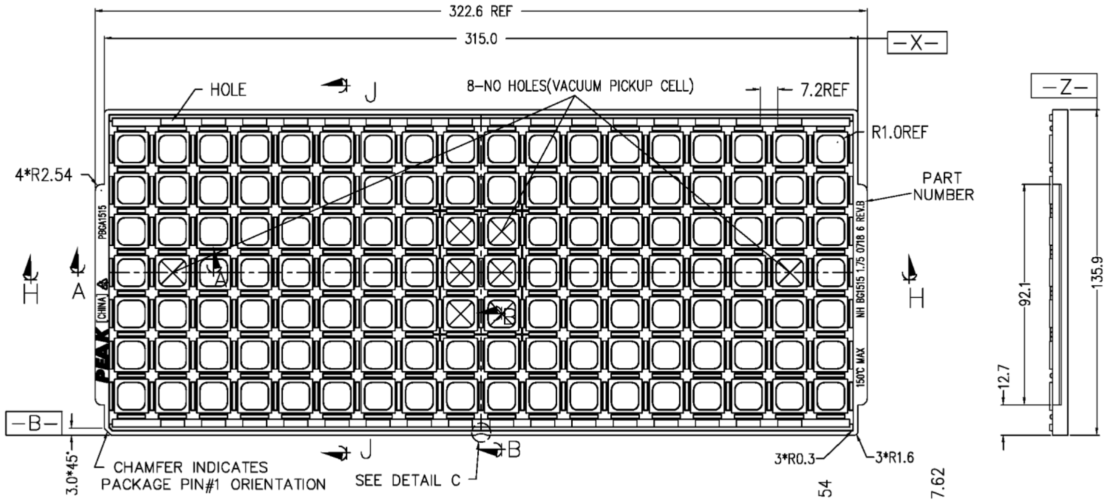
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	8	17	136	18.10	15.00	12.70	15.45	5+1
MTAI	150C	8	17	136	18.10	15.00	12.70	15.45	5+1

2TC (FCCSP 196L 15X15mm) Tray drawing

ASE9



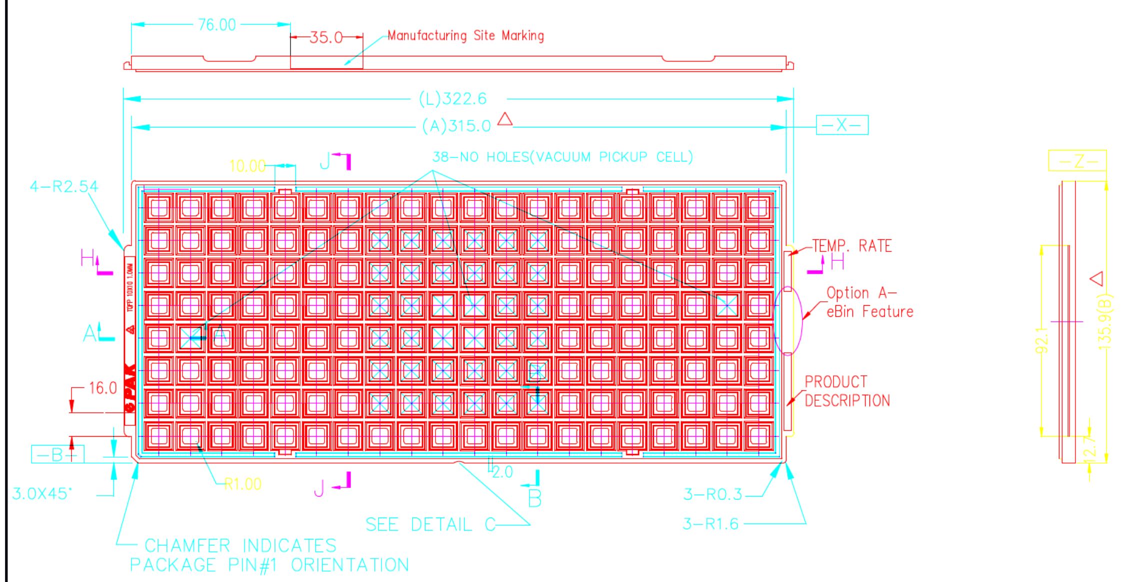
MTAI



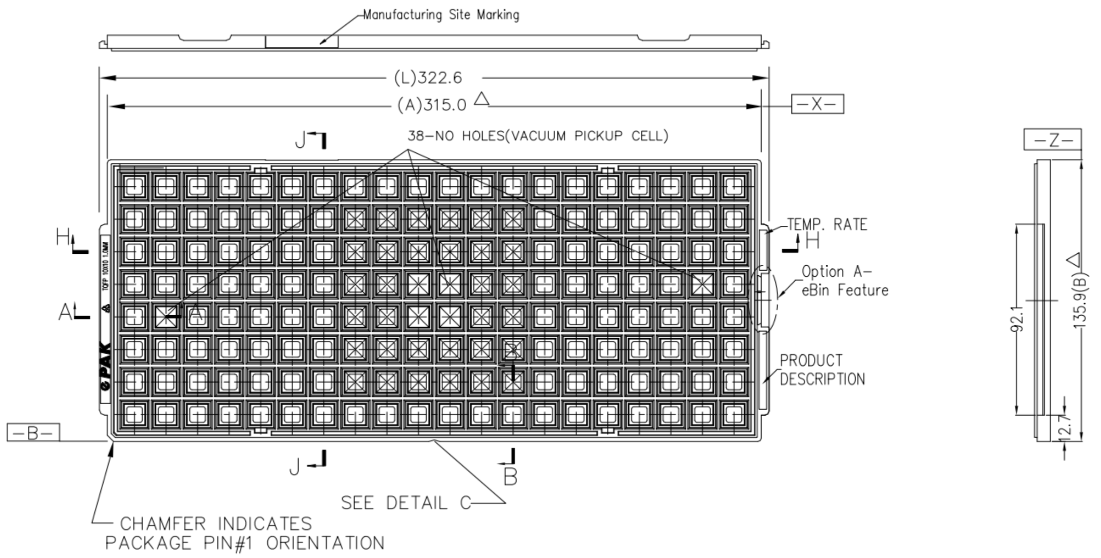
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	7	18	126	17.20	17.20	11.30	16.35	5+1
MTAI	150C	7	18	126	17.20	17.20	11.30	16.35	5+1

3QC (TQFP 64L 10x10x1.0mm) Tray drawing

ASE9



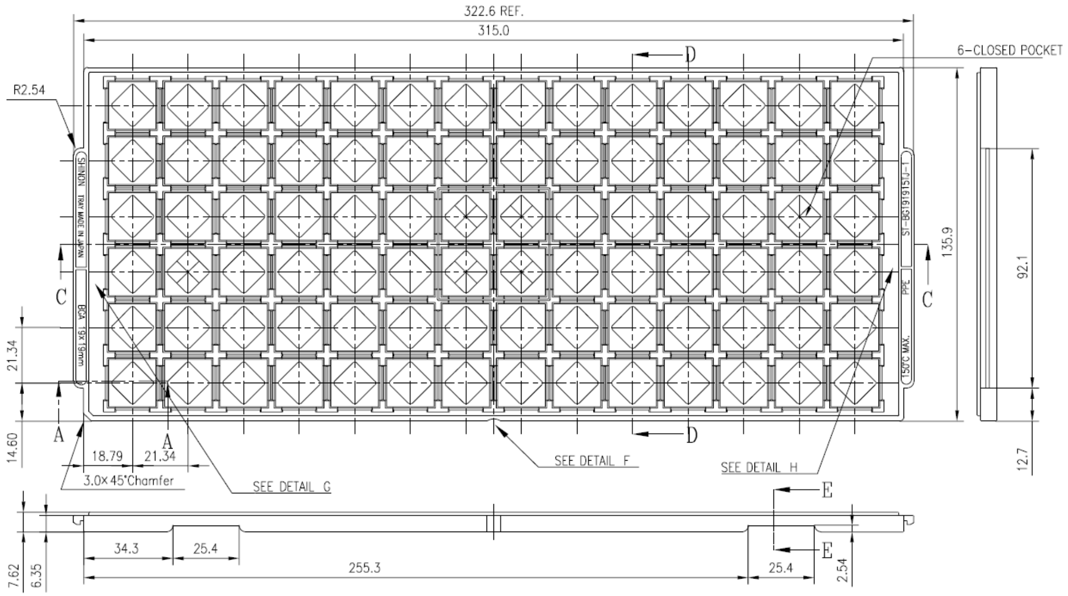
MTAI



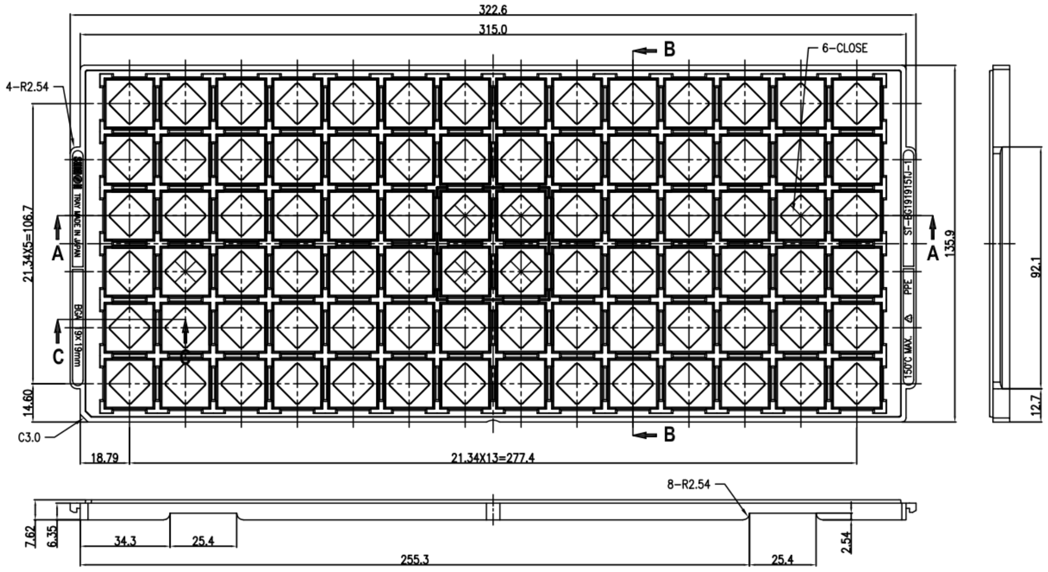
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	8	20	160	15.20	15.70	13.10	13.00	5+1
MTAI	150C	8	20	160	15.20	15.70	13.10	13.00	5+1

3KC (HFCBGA 324L 19x19mm) Tray drawing

ASE9



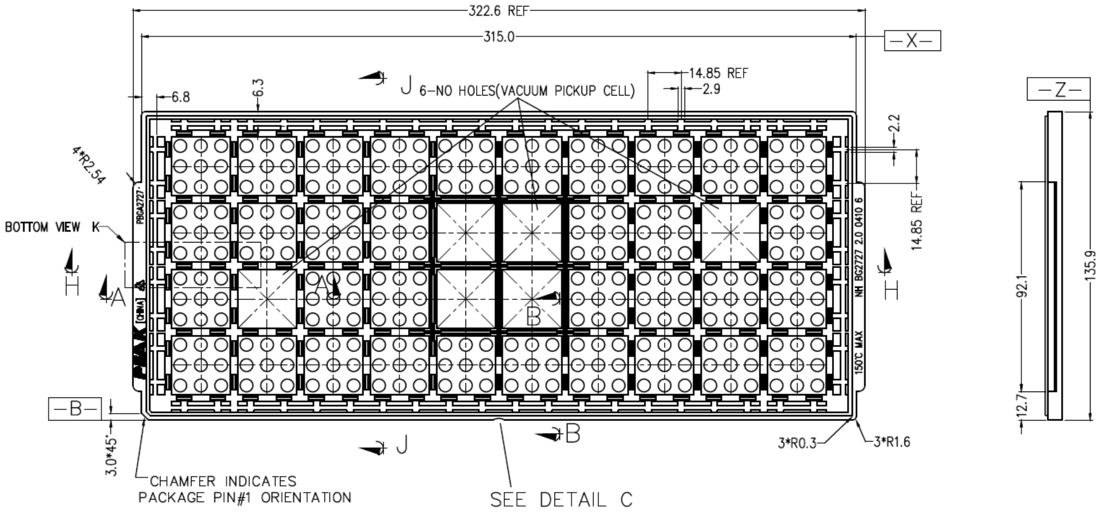
MTAI



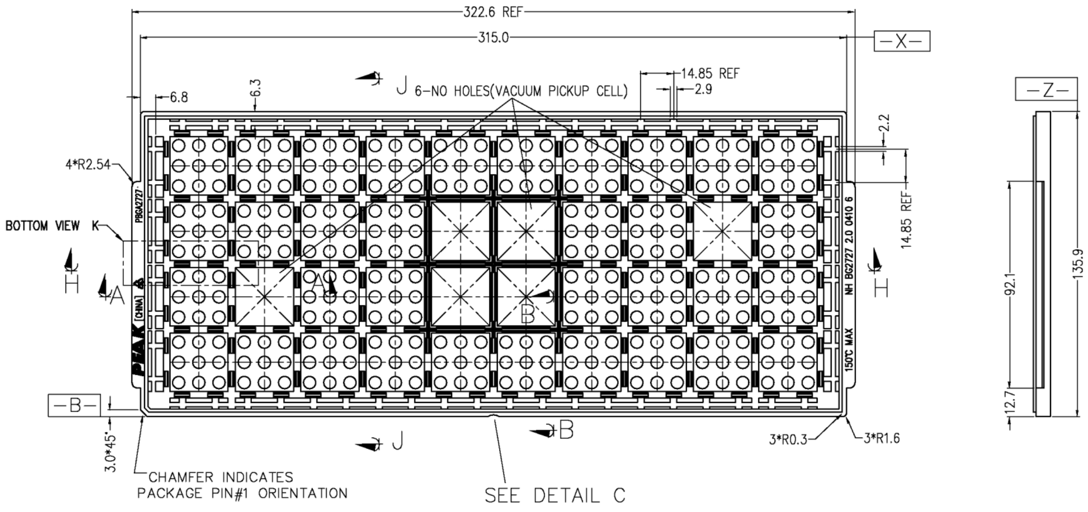
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	6	14	84	21.34	21.34	18.79	14.60	5+1
MTAI	150C	6	14	84	21.34	21.34	18.79	14.60	5+1

3PC (HSBGA 444L 27x27mm) Tray drawing

ASE9



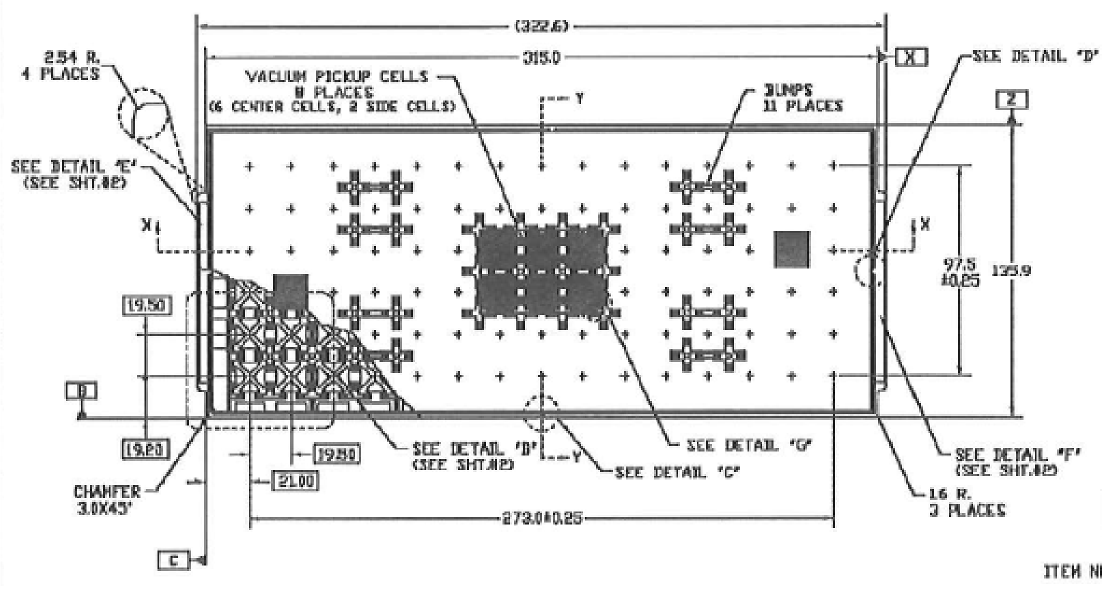
MTAI



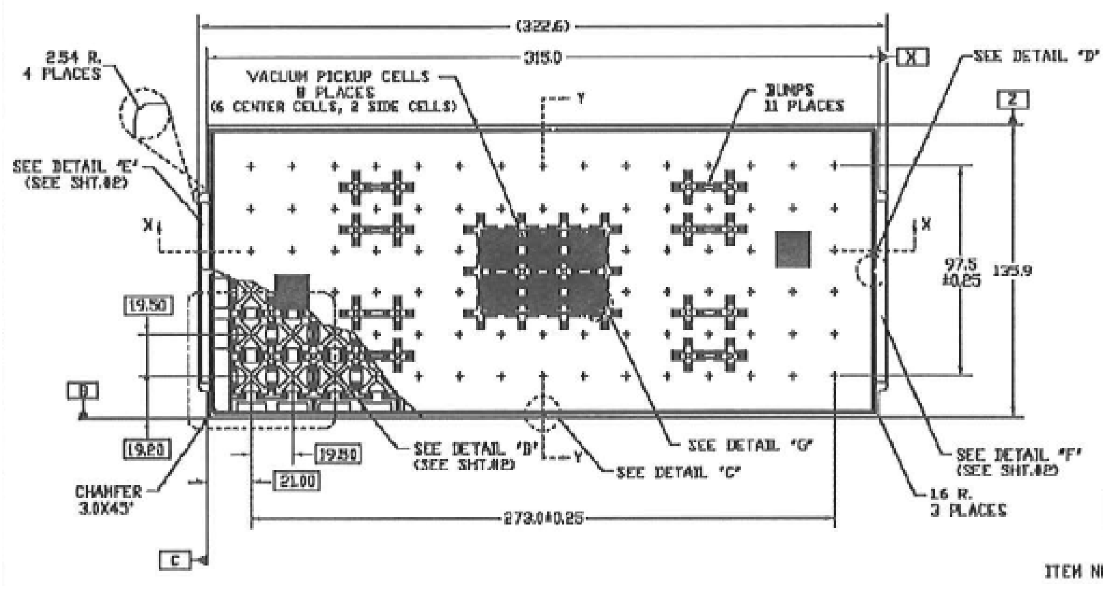
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	4	10	40	29.20	29.20	26.10	24.15	5+1
MTAI	150C	4	10	40	29.20	29.20	26.10	24.15	5+1

3EC (256L PBGA 17x17mm) Tray drawing

ASE9



MTAI



Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Pocket Pitch (X) mm	Pocket Pitch (Y) mm	Outer Pocket center to Tray edge (X) mm	Outer Pocket center to Tray edge (Y) mm	Tray Stack
ASE9	150C	6	15	90	19.50	19.50	21.00	19.20	5+1
MTAI	150C	6	15	90	19.50	19.50	21.00	19.20	5+1

QUALIFICATION REPORT SUMMARY

PCN #: ASER-17HAXZ310

Date:
September 24, 2020

Qualification of MTAI as an additional final test site for selected Microsemi ENT products available in 138L QFN package. Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages.

Purpose: **Qualification of MTAI as an additional final test site for selected Microsemi ENT VSC849xxx, VSC722xxx, VSC751xxx, VSC848xxx, VSC334xxx, VSC822xxx, VSC824xxx and VSC865xxx device families available in 196L FCBGA, 144L FCCSP, 324L, 484L and 780L HFCBGA, 444L HSBGA, 64L TQFP and 172L VQFN packages.**

CCB No.: **3740, 3740.001, 3740.002, 3740.003 and 3740.004**

Test / Evaluation	Test Conditions / Parameters	Result
Test comparison	• Select 50 good sample - test using the original platform and retest using destination platform. • The selected measured parameter should be within +/-10% variation between original and destination platform.	Passed
Fresh lot run	• Select 1 fresh lot. Lot quantity is 3,000 units. Test using the new test location platform. Then cross correlate with original test location platform. • Bin to bin difference should be within 0.1%.	Passed